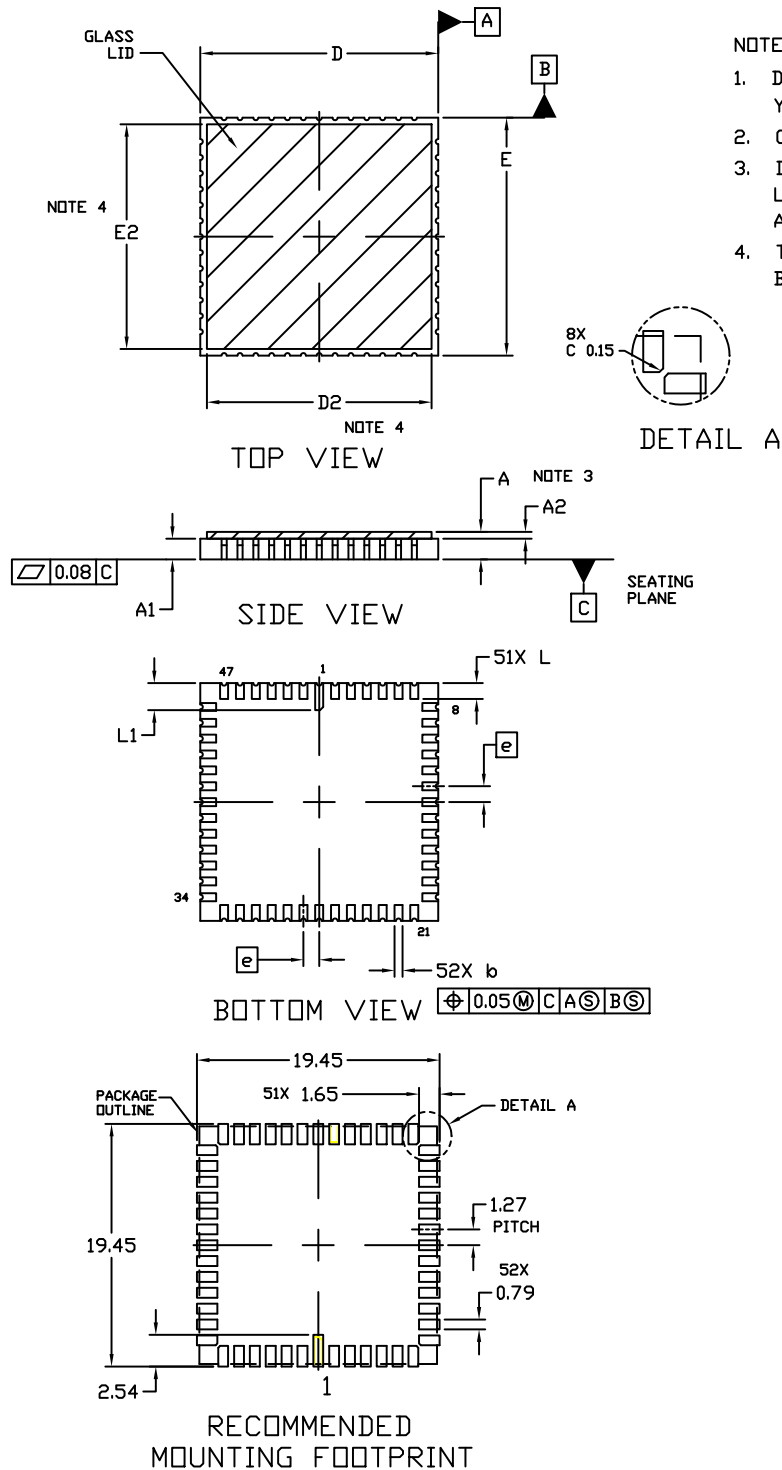


LCC52, 19.05x19.05
CASE 115AP
ISSUE O

DATE 30 JUN 2011

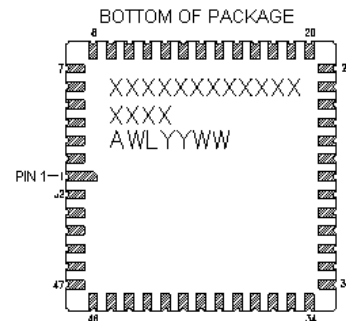


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.

DIM	MILLIMETERS	
	MIN.	MAX.
A	1.85	2.55
A1	1.65	REF
A2	0.55	REF
b	0.56	0.72
D	18.80	19.43
D2	18.00	REF
E	18.80	19.43
E2	18.00	REF
e	1.27	BSC
L	1.14	1.40
L1	1.96	2.36

GENERIC MARKING DIAGRAM



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
NNNN = Serial Number

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